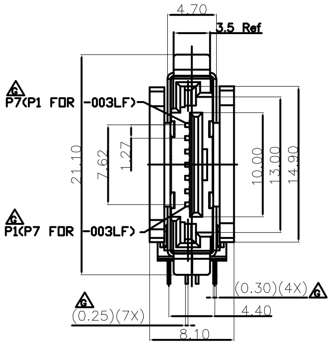
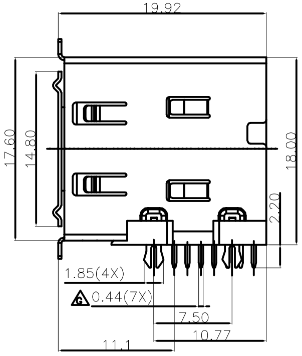
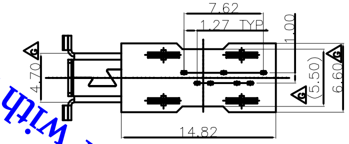
PRODUCT NO.
10074141-001LF
10074141-003LF
G

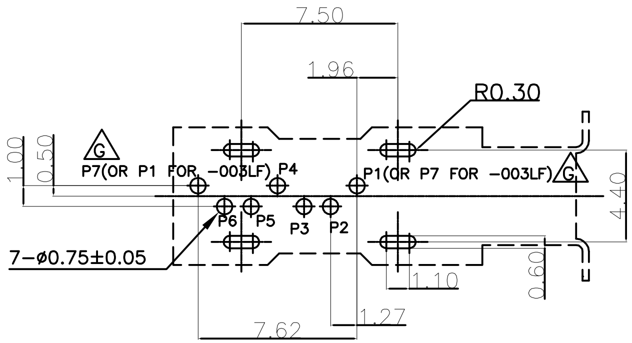


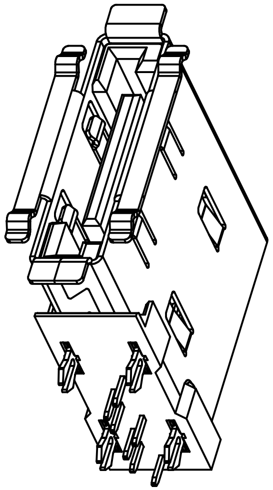


NOTES:
1.MATERIAL:
HOUSING:THERMALPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
COLOR:BLACK
CONTACT:COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
100u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
SHELL/BOARD LOCK:50 u" MIN.NICKEL PLATING OVER ALL
3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC
IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB

4. PRODUCT SPEC : GS-12-386
PACKING SPEC : GS-14-1109
5. PRODUCT NUMBERING:
10074141 -0 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
3: 15u" GOLD PLATING WITH NEW PINOUT ASSIGNMENT G
0: LAYOUT#1
6. A SYMBOL G WILL BE NEXT TO ANY DIMENSION,
VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH
THE CURRENT DRAWING REVISION







PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A–
P4	GND
P5	B–
P6	B+
P7	GND

RECOMMEND P.C.BOARD LAYOUT
PCB TOLERANCE:±0.05

mat'l. code	surface	tolerance	projection	product family
14	ISO 1302 58	ISO 406 ISO 1101		533

ltr	ecn no	dr	date
A	T07-1074	S.LIN	2007-05-23
B	T08-1082	S.LIN	2008-04-29
C	T10-0184	S.LIN	2010-12-14
D	T-005440	S.LIN	2011-08-31
E	ELX-S-007081	HKL	2011-10-17
F	ELX-S-011879	HKL	2012-06-08
G	ELX-S-23409	HKL	2016-03-03

tolerances unless otherwise specified

angles	linear	.X±0.38	MM
		.XX±0.25	
0°±2°		.XXX±0.100	scale 2:1

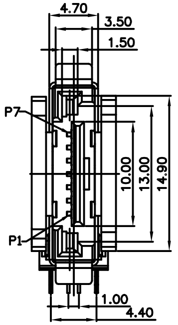
dr	STERLING.LIN	2007-05-21
engr	HKLIM	2016-03-03
chr	HKLIM	2016-03-03
appd	KPTAY	2016-03-03

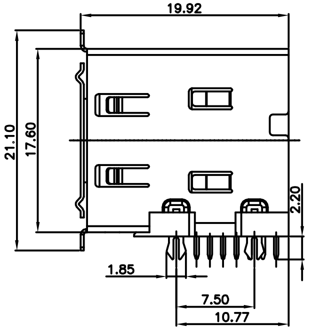
Amphenol FCi

title
E-SATA_UP_RIGHT
DIP_TYPE

dwg no 10074141
sheet 1 of 3
size A3
type PRODUCT-CUSTOMER_DRW Drawing

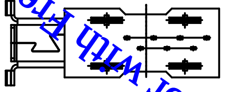
sheet index	revision	G	G	G	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

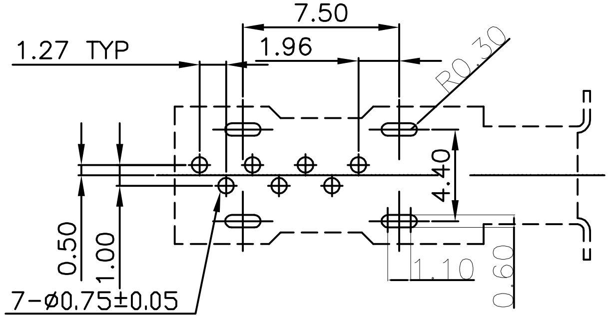




NOTES:
1.MATERIAL:
HOUSING:THERMALPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
COLOR:BLACK
CONTACT:COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
100u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
BOARD LOCK:50u" MIN.NICKEL PLATING OVER ALL
80u" MIN.MATT TIN PLATING OVER ALL
SHELL/BOARD LOCK:50u" MIN.NICKEL PLATING OVER ALL
3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC
IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB

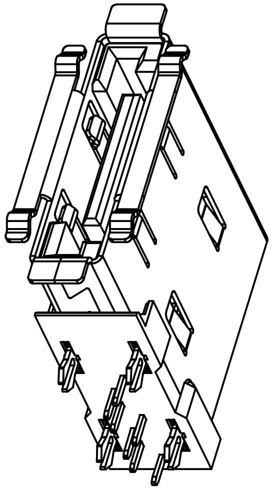
4. PRODUCT SPEC : GS-12-386
PACKING SPEC : GS-14-1109
5. PRODUCT NUMBERING:
10074141 -1 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
1: LAYOUT#2
6. A SYMBOL ⚠G WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH
HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION





P.C.BOARD MOUNTING DIMENSIONS T=1.60mm

PCB TOLERANCE: ±0.05



PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A−
P4	GND
P5	B−
P6	B+
P7	GND

mat'l. code 14

surface 58 ✓ ISO 1302

tolerance ISO 406 ISO 1101

projection

product family 533

ltr	ecn no	dr	date
A	T07-1074	S.LIN	2007-05-23
B	T08-1082	S.LIN	2008-04-29
C	T10-0184	S.LIN	2010-12-14
D	T-005440	S.LIN	2011-08-31
E	ELX-S-007081	HKL	2011-10-17
F	ELX-S-011879	HKL	2012-06-08
G	ELX-S-23409	HKL	2016-03-03

tolerances unless otherwise specified

angles	linear	
0°±2°	.X±0.38	
	.XX±0.25	
	.XXX±0.100	

MM

scale 2:1

dr	STERLING.LIN	2007-05-21
engr	HKLIM	2016-03-03
chr	HKLIM	2016-03-03
appd	KPTAY	2016-03-03

Amphenol FCi

title
E-SATA_UP_RIGHT
DIP_TYPE

dwg no 10074141

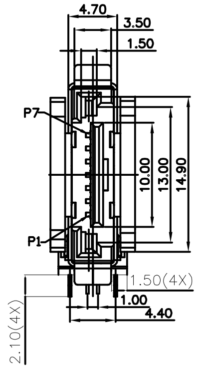
sheet 2 of 3

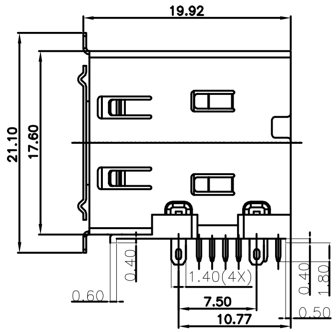
size A3

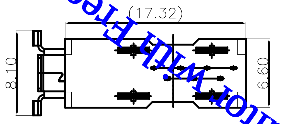
type PRODUCT-CUSTOMER_DRW Drawing

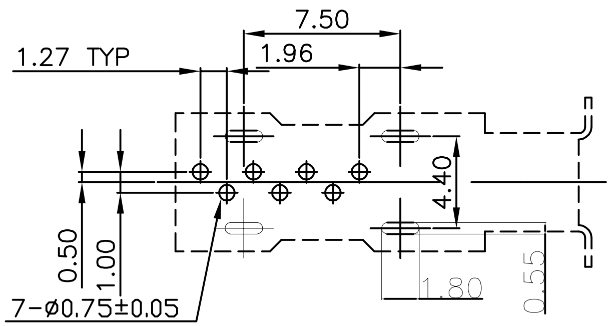
sheet index	revision	G	G	G	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

NOTES:
1.MATERIAL:
HOUSING: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
COLOR:BLACK
CONTACT: COPPER ALLOY
SHELL/BOARD LOCK: COPPER ALLOY
2.FINISH:
CONTACT:GOLD PLATING ON CONTACT AREA
120u" MIN. MATT TIN PLATING ON SOLDERTAILS
50u" MIN.NICKEL UNDERPLATING OVER ALL
BOARD LOCK: 50u" MIN.NICKEL PLATING OVER ALL
120u" MIN.MATT TIN PLATING OVER ALL
SHELL/BOARD LOCK: 50u" MIN.NICKEL PLATING OVER ALL
3. THE HOUSING WILL WITHSTAND TO 260C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB
4. PRODUCT SPEC : GS-12-386
PACKING SPEC : GS-14-1109
5. PRODUCT NUMBERING:
10074141 -2 0 X X LF —— LEAD FREE
PACKING:
BLANK: TRAY PACKING
1: 15u" GOLD PLATING
2: G/F GOLD PLATING
2: LAYOUT#3
6. A SYMBOL ⚠G WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION









P.C.BOARD MOUNTING DIMENSIONS T=1.60mm

PCB TOLERANCE: ±0.05

PIN DEFINITON

ESATA	
NAME	TYPE
P1	GND
P2	A+
P3	A–
P4	GND
P5	B–
P6	B+
P7	GND

mat'l. code	surface	tolerance	projection	product family
14	ISO 1302 58	ISO 406 ISO 1101		533

tolerances unless otherwise specified

angles	linear	
0°±2°	.X±0.38	MM
	.XX±0.25	
	.XXX±0.100	scale 2:1

ltr	ecn no	dr	date
A	T07-1074	S.LIN	2007-05-23
B	T08-1082	S.LIN	2008-04-29
C	T10-0184	S.LIN	2010-12-14
D	T-005440	S.LIN	2011-08-31
E	ELX-S-007081	HKL	2011-10-17
F	ELX-S-011879	HKL	2012-06-08
G	ELX-S-23409	HKL	2016-03-03

dr	STERLING.LIN	2007-05-21
engr	HKLIM	2016-03-03
chr	HKLIM	2016-03-03
appd	KPTAY	2016-03-03

Amphenol FCi

title
E-SATA_UP_RIGHT
DIP_TYPE

dwg no 10074141 sheet 3 of 3 size A3

type PRODUCT-CUSTOMER_DRW Drawing

sheet index	revision	1	2	3	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139
	sheet	G	G	G	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138